



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-10-02
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LMV324IYPT	KD6R*V324AS6	A	BO2A	2017-10-02
	Amount	UoM	Unit type	ST ECOPACK Grade
	54.82	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5x4.4x0.9	14	gull wing	
Comment	Package: 6R TSSOP 14 BODY 4.4 PITCH 0.65			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KD6R*V324A56				5000003.0	1000017.0	
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	2.975	mg	supplier	die	Silicon (Si)	7440-21-3		2.951	mg	991933	53831	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	3361	182	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	2689	146	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	2017	109	
Leadframe	M-004 Copper and its alloys	27.334	mg	supplier	alloy	Copper (Cu)	7440-50-8		26.632	mg	974318	485808	
				supplier	alloy	Iron (Fe)	7439-89-6		0.626	mg	22902	11419	
				supplier	alloy	Zinc (Zn)	7440-66-6		0.033	mg	1207	602	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.040	mg	1463	730	
	M-008 Precious metals		supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	37	18		
	M-008 Precious metals		supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	37	18		
			supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	37	18		
	Die attach	M-015 Other organic materials	1.066	mg	supplier	glue	Silver (Ag)	7440-22-4		0.937	mg	878987	17092
					supplier	glue	Isobornyl Methacrylate	7534-94-3		0.053	mg	49719	967
					supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.053	mg	49719	967
supplier					glue	Acrylate polymer	87320-05-6		0.021	mg	19700	383	
supplier					glue	Epoxyhexahydroxyethyltrimethoxysilane	3388-04-3		0.001	mg	938	18	
supplier					glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	938	18	
Bonding wires	M-011 Other inorganic materials	0.076	mg	supplier	wire	Copper (Cu)	7440-50-8		0.076	mg	1000000	1386	
Encapsulation	M-011 Other inorganic materials	23.370	mg	supplier	mold compound	Silica, vitreous	60676-86-0		20.495	mg	876979	373860	
				supplier	mold compound	Epoxy resin	85954-11-6		0.935	mg	40009	17056	
				supplier	mold compound	Epoxy	29690-82-2		0.935	mg	40009	17056	
				supplier	mold compound	phenol resin	Proprietary		0.701	mg	29996	12787	
				supplier	mold compound	additive	Proprietary		0.234	mg	10013	4269	
			supplier	mold compound	carbon black	1333-86-4		0.070	mg	2995	1277		